

Leahkinn Technology Limited
Roadmap Q1 2020



Your Design & Business Partner in Mobile & Computing Industry





LPDDR
eMMC
eMCP
NAND MCP
Others



LPDDR

LPDDR2 168/178B



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
4Gb	38nm LP2 x1	 				
8Gb	38nm LP2 x2	 				

 Build To Order

 End of Life

LPDDR

LPDDR3 178B











Density	Technology	Q1	Q2	Q3	Q4	Q1 21
4Gb	25nm LP3 x1	● → EoL				
8Gb	20nm LP3 x1	● →				
16Gb	20nm LP3 x2	● →				
24Gb	20nm LP3 x3	● BTO →				
32Gb	20nm LP3 x4	● BTO →				

LPDDR

LPDDR3 256B PoP



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
16Gb	20nm LP3 x2	 				
32Gb	20nm LP3 x4	 				

LPDDR

LPDDR4 200B













Density	Technology	Q1	Q2	Q3	Q4	Q1 21
4Gb	20nm LP4 x1	● BTO	→			
8Gb	20nm LP4 x1	●	→	EoL		
16Gb	20nm LP4 x2	●	→		EoL	
16Gb	18nm LP4 x2	●	→			
24Gb	20nm LP4 x3	● BTO	→		EoL	
24Gb	17nm LP4 x2	●	→			
32Gb	20nm LP4 x4	●	→	EoL		
32Gb	18nm LP4 x4	● BTO	→			

eMMC

eMMC V5.1 153B





Density	Technology	Q1	Q2	Q3	Q4	Q1 21
8GB	2D MLC x1					
16GB	3D TLC x1					
32GB	3D TLC x1					
64GB	3D TLC x2	 				

eMCP

LP2 eMCP V5.1 162B



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
8GB + 4Gb	2D MLC x1 + 38nm LP2 x1	 BTO				
8GB + 8Gb	2D MLC x1 + 38nm LP2 x2	 BTO				

eMCP

LP3 eMCP V5.1 221B



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
8GB + 8Gb	2D MLC x1 + 20nm LP3 x1					
16GB + 8Gb	3D TLC x1 + 20nm LP3 x1					
16GB + 16Gb	2D MLC x2 + 20nm LP3 x2					
16GB + 16Gb	3D TLC x1 + 20nm LP3 x2					
32GB + 24Gb	2D MLC x4 + 25nm LP3 x4					

eMCP

LP4 eMCP V5.1 254B



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
16GB + 16Gb	3D TLC x1 + 18nm LP4 x2	QS	MP			
32GB + 16Gb	3D TLC x1 + 18nm LP4 x2		QS	MP		
32GB + 24Gb	3D TLC x1 + 17nm LP4 x2	QS	MP			

NAND MCP

LP2 MCP 162B





Density	Technology	Q1	Q2	Q3	Q4	Q1 21
2Gb + 2Gb	24nm SLC x1 + 38nm LP2 x1	●				
4Gb + 2Gb	24nm SLC x1 + 38nm LP2 x1	●				
4Gb + 4Gb	24nm SLC x1 + 38nm LP2 x1	●				



Other

DDR3/3L 78B



Density	Technology	Q1	Q2	Q3	Q4	Q1 21
4Gb	512Mx8					

DDR3/3L 96B

Density	Technology	Q1	Q2	Q3	Q4	Q1 21
4Gb	256Mx16					

Others

A. Leahkinn can customize different parameters to fit customers' requirement

- **Ball Out (134B, 168B, 253B, 256B, 272B, 366B and etc.)**
- **NAND / DRAM combination**
- **Speed / Power Budget**
- **Specific Test Flow**

B. Leahkinn also offered ODM business model for customized memory products

- **Hybrid Design (Different Die Size)**
- **ASIC + Memory SiP experience**